



Cooperative Microsystems

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Report Documentation Page				Form Approved OMB No. 0704-0188	
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1. REPORT DATE 04 MAR 2009		2. REPORT TYPE		3. DATES COVERED 00-00-2009 to 00-00-2009	
4. TITLE AND SUBTITLE Cooperative Microsystems				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) Defense Advanced Research Projects Agency, Microsystems Technology Office (MTO), 3701 North Fairfax Drive, Arlington, VA, 22203				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT Approved for public release; distribution unlimited					
13. SUPPLEMENTARY NOTES					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT Same as Report (SAR)	18. NUMBER OF PAGES 19	19a. NAME OF RESPONSIBLE PERSON
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified			

MTO Symposium
2-5 March 2009 – San Jose, California

“Cooperative Microsystems”

Adel A. M. Saleh

DARPA / MTO

4 March 2009

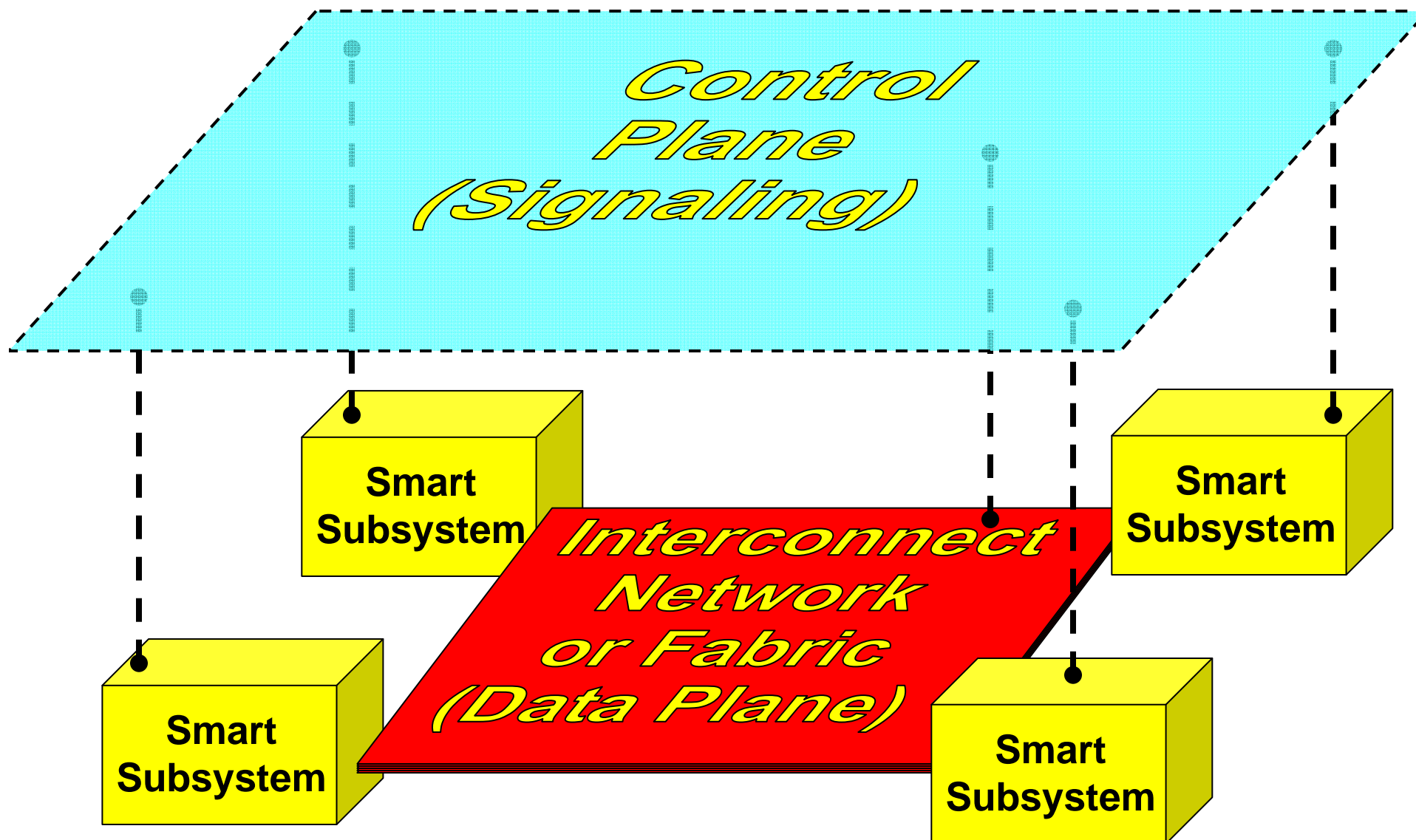


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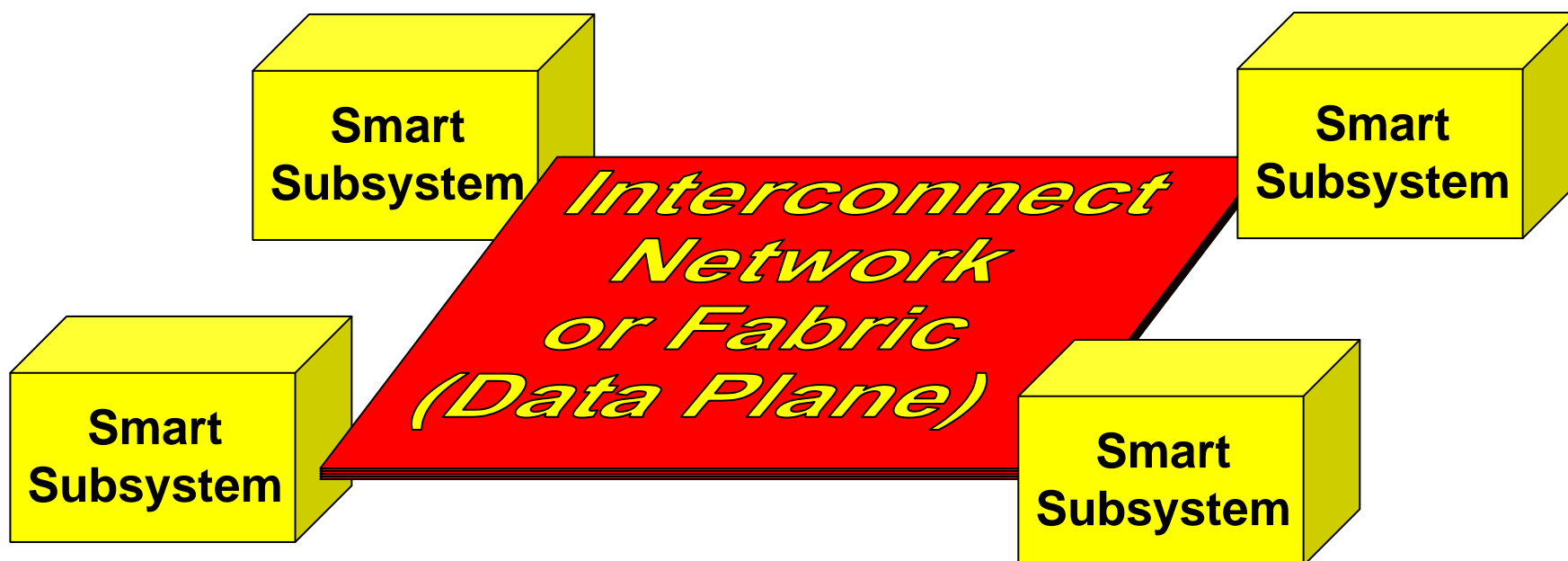


Definition of a Cooperative System





Definition of a Cooperative System





A Cooperative **Mega-System** (Global-Scale IP/Optical Network)



DARPA CORONET Program

The Network Nodes Cooperate to Accomplish:

- Fast, automatic end-to-end provisioning of IP and Optical Services
- Fast, automatic recovery from multiple network failures (self healing)
- Secure, low blocking, low latency, high efficiency, and huge capacity

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Let Us Shrink the Network by Factors of 10 Each Case is a Cooperative System of Its Own



~5,000 km



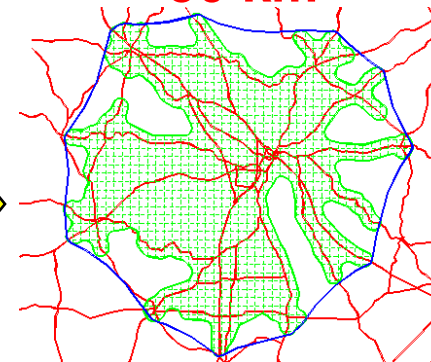
Wide-Area Network (WAN)

~500 km



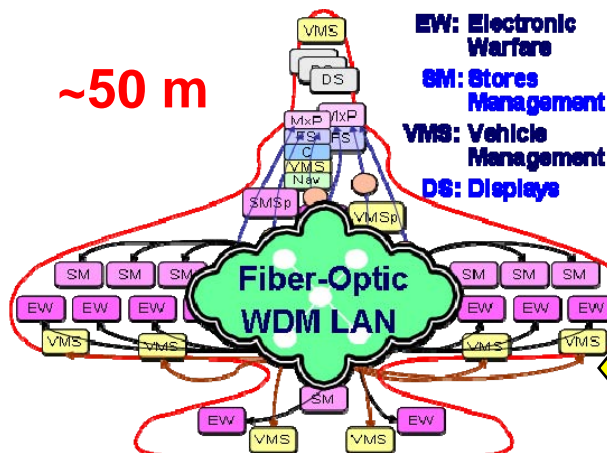
Regional Network

~50 km



Greater Metropolitan-Area Network (MAN)

~50 m



WDM Local-Area Network (LAN) for Avionic Platforms
DARPA NEW-HIP Program

~500 m



Campus-Scale Local-Area Network (LAN)

~5 km



Metropolitan-Area Network (MAN)



Outline of the Rest of the Talk



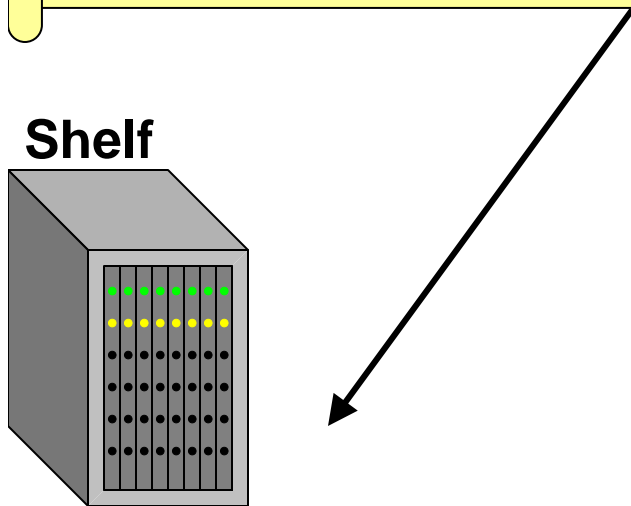
- A Vision for the Next-Generation, High-Performance Cooperative Microsystems Consisting of Chips, Cards, Shelves and Racks
- Chip-to-Chip Optical Interconnects
 - *Current and Future Vision*
- On-Chip Cooperative Microsystems
 - *We will hear two talks on this*
- Summary of the Vision
- Quantum-Scale Cooperative Microsystems
 - *We will hear two talks on this*
- Biological Cooperative Microsystems
 - *We will hear one talk on this*



A Vision for the Next-Generation, High-Performance Cooperative Microsystems



The Heart of the Vision is Configurable, Optical, WDM-Based Interconnects to Realize a Plug-and-Play, Multi-Terabit Bus



Shelf

**Optical
Backplane**

**Micro-
Chips**

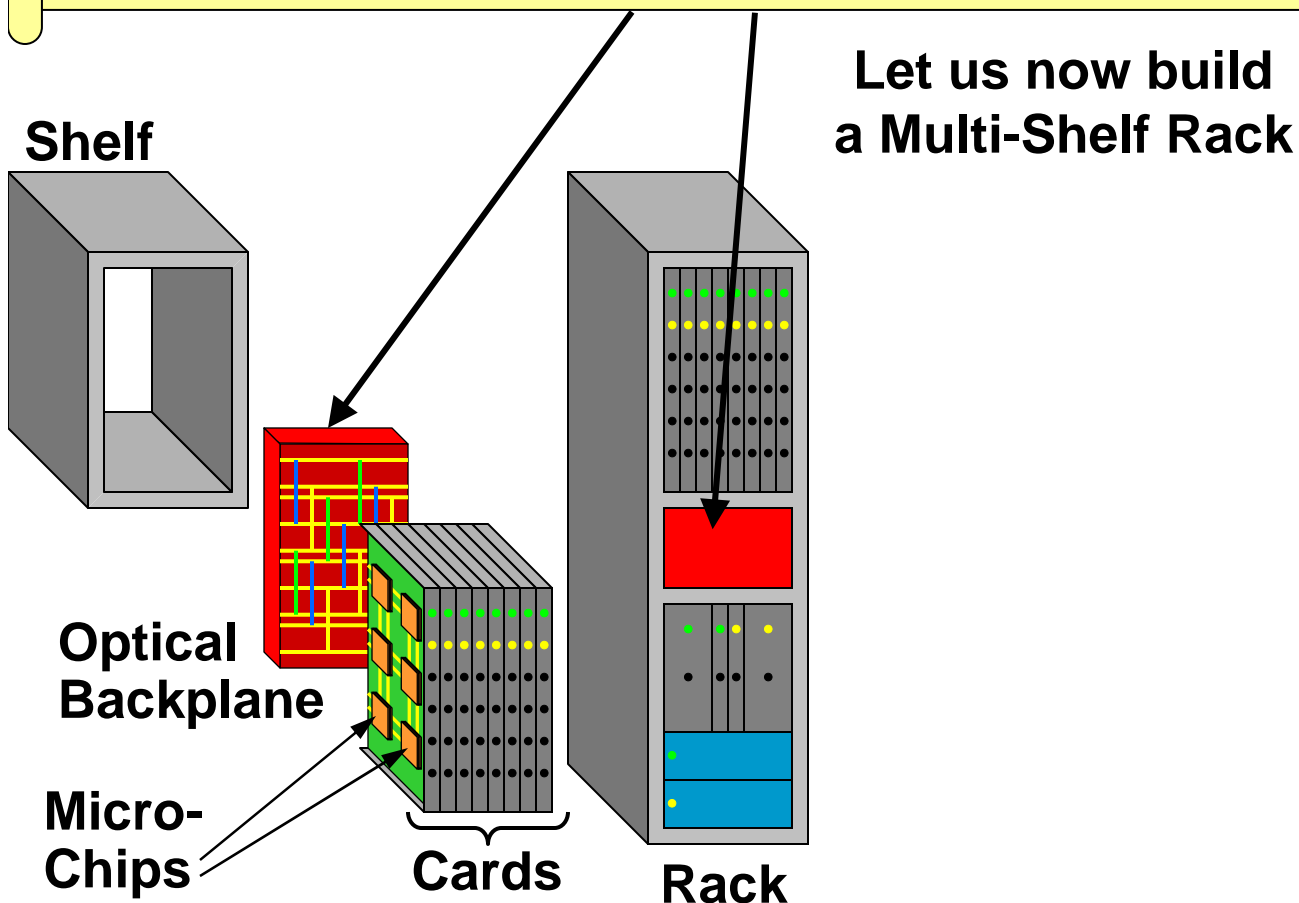
Cards



A Vision for the Next-Generation, High-Performance Cooperative Microsystems



The Heart of the Vision is Configurable, Optical, WDM-Based Interconnects to Realize a Plug-and-Play, Multi-Terabit Bus

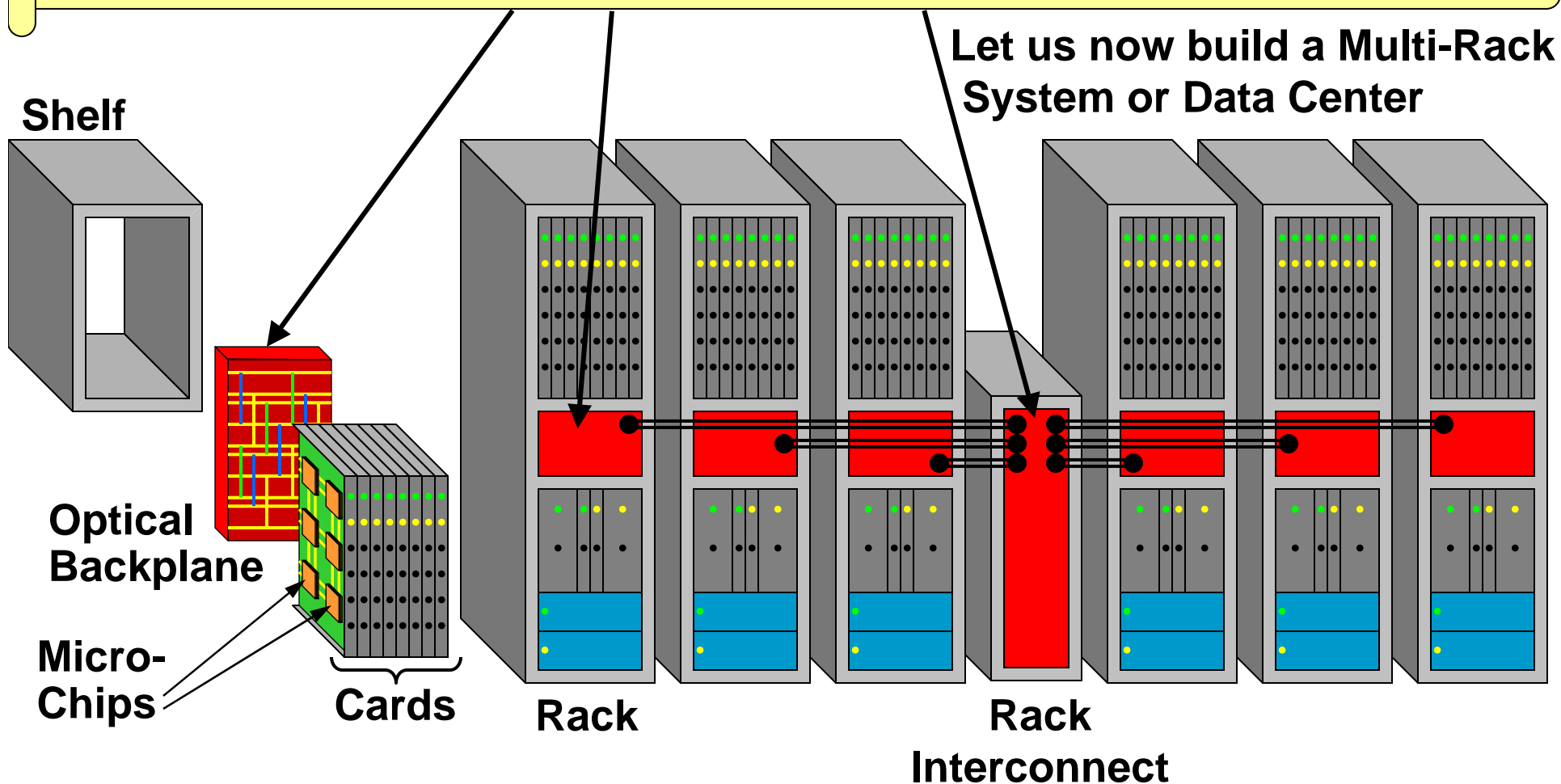




A Vision for the Next-Generation, High-Performance Cooperative Microsystems

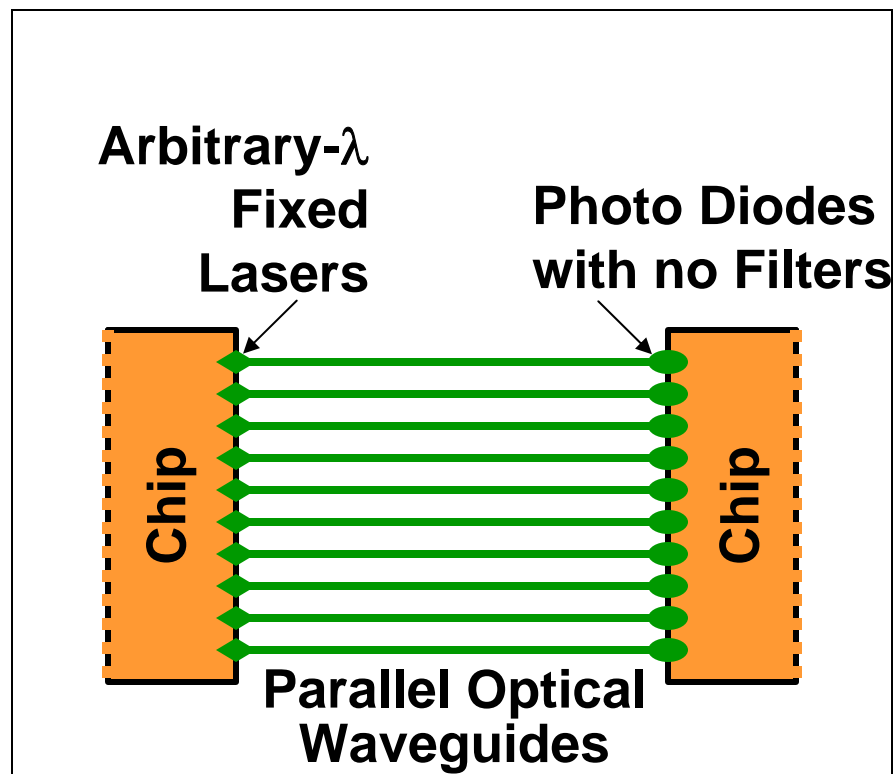


The Heart of the Vision is Configurable, Optical, WDM-Based Interconnects to Realize a Plug-and-Play, Multi-Terabit Bus



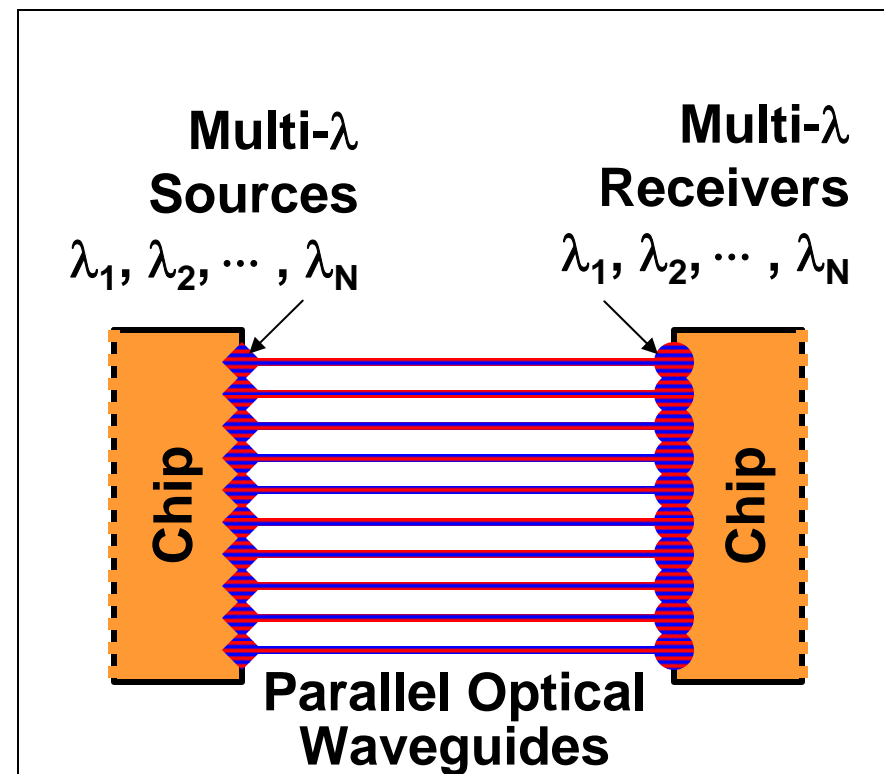


Why/How to Add WDM and Configurability ?



Static, Parallel Optical Interconnect

* *Reference architecture*

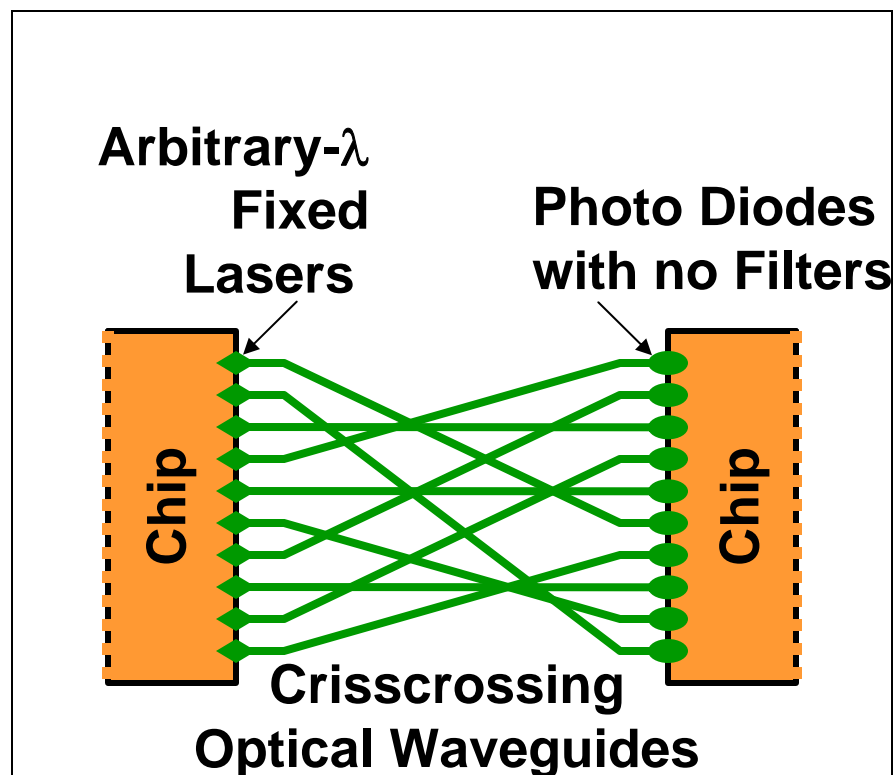


Use WDM to Increase Capacity ?

- * *Multi-λ transmitters and receiver are large and power hungry*
- * *I do not believe that this is why one would want to do WDM*

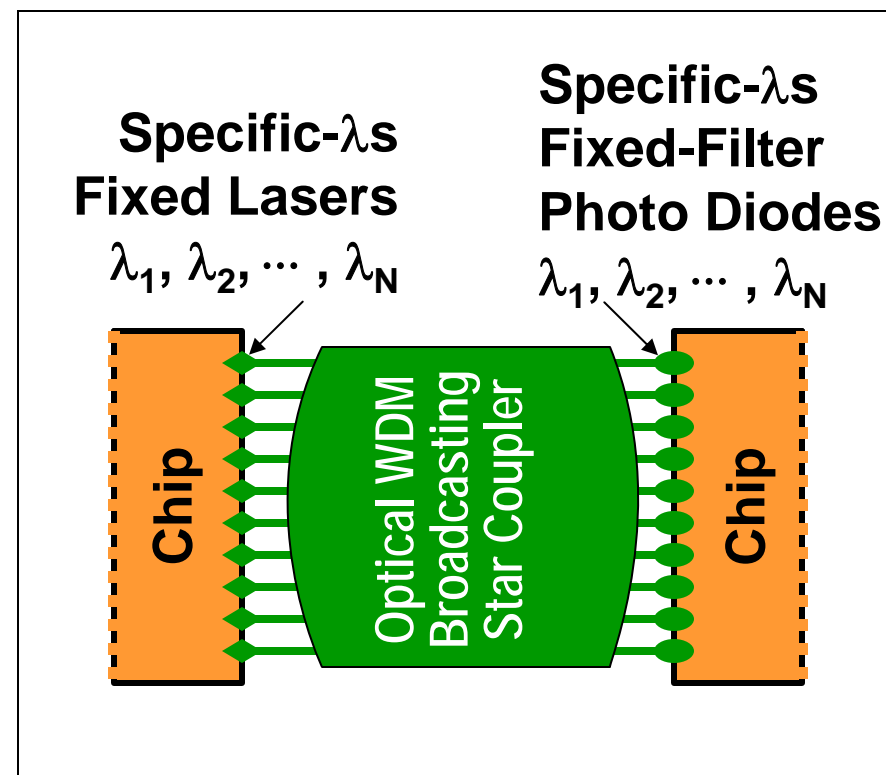


Why/How to Add WDM and Configurability ?



Crisscrossing Optical Interconnect

- * *Hard to fabricate crossing waveguides with low loss and low cross-talk*
- * *Once made, interconnection is static*
- * *Not an elegant solution!*

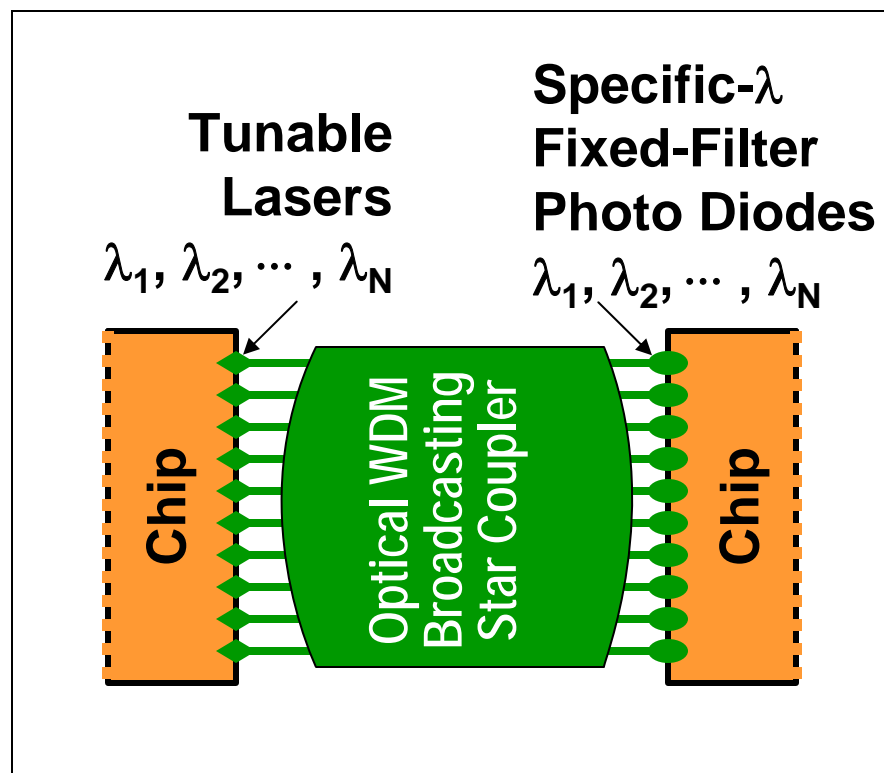


Crisscrossing Optical Interconnect

- * *More elegant solution*
- * *But, we need specific-λs, fixed lasers and filters for this vision*
- * *Nominal loss = 1/N*
- * *WDM in the fabric, not at the ends*

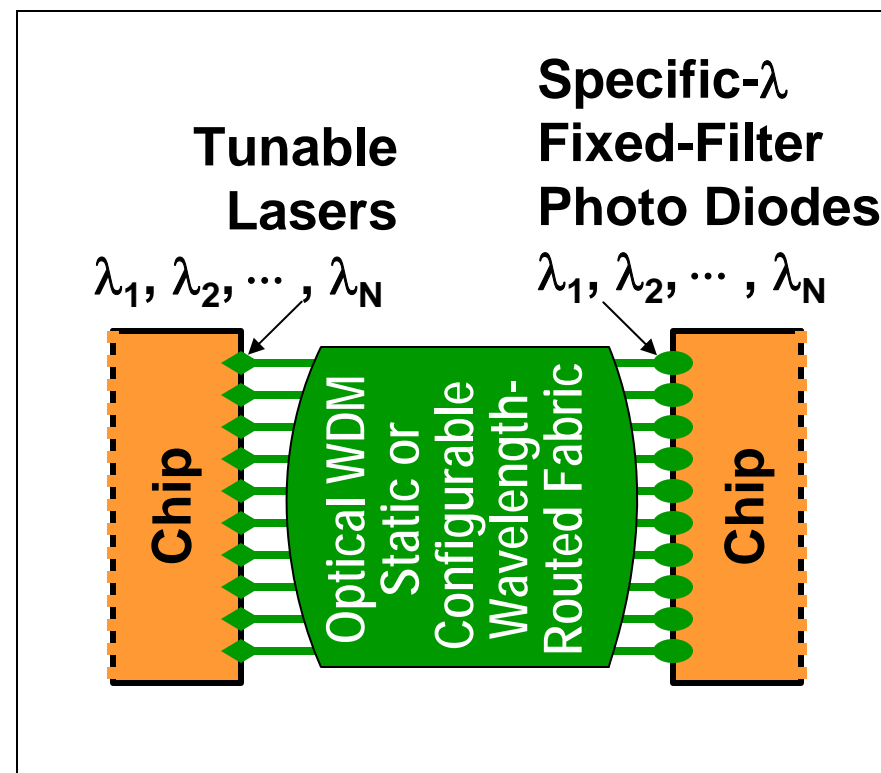


Why/How to Add WDM and Configurability ?



Configurable Optical Interconnect

- * *We need tunable lasers and specific- λ s fixed filters for this vision*
- * *Nominal loss = $1/N$*
- * *WDM in the fabric not at the ends*

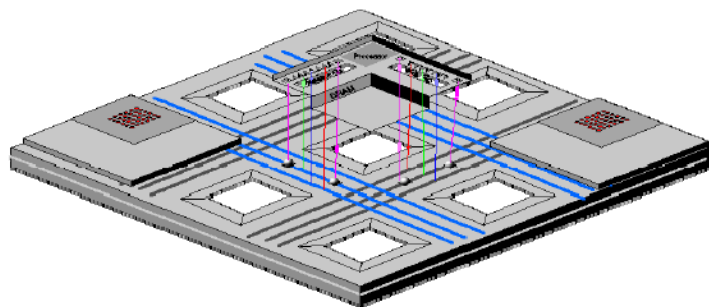


Configurable Optical Interconnect

- * *Same end device requirements*
- * *The fabric can be a static AWG or a tunable cross-bar switch*
- * *No nominal $1/N$ loss*
- * *WDM in the fabric not at the ends*



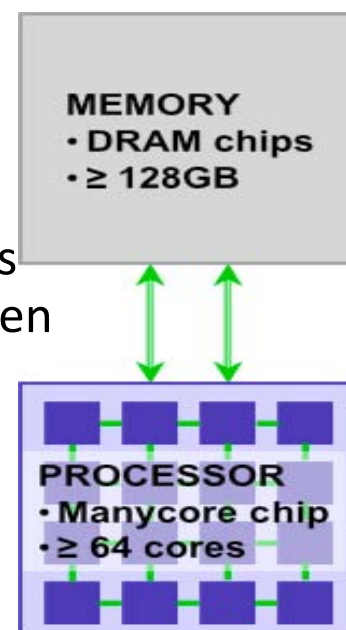
Moving the Vision On-Chip !



The DARPA UNIC Program: Ultraperformance Nanophotonic Intrachip Communications

SUN Microsystems: Macrochip design providing 10 TB/s bisection bandwidth for 64 cores providing 10 TFLOPS

MIT Lincoln Lab:
Optimization of optical communication networks among cores, and between cores and memory

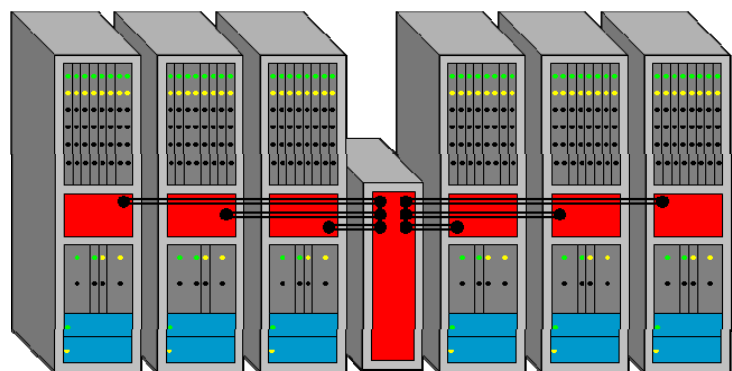


Two Talks:

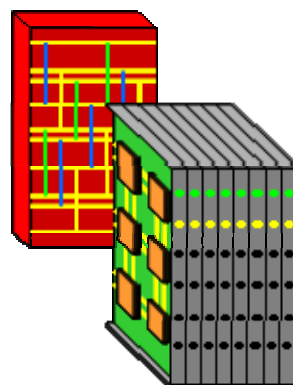
- Ashok Krishnamoorthy (SUN) – **Intrachip Photonic Communications Networks with Seamless Off-chip Communications: Vision for the Future**
- Jeremy Kepner (MIT/LL) – **Photonic-enabled Optimized Embedded Microprocessors, Shared Memory Optimizing Multicore Cooperation**



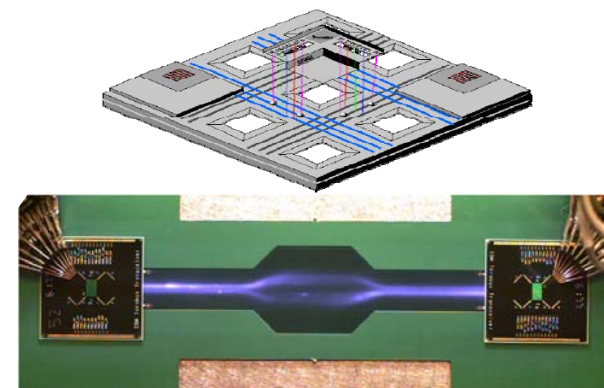
Cooperative Systems of Various Orders of Magnitudes Benefiting from WDM Optical Networking



Intra- / Inter-Rack



Inter-Cards or Boards



Intra- / Inter-Chip

- Of course, the very same devices and components do not work at all scales of the vision
- But the same basic ideas and architectures promise higher performance (capacity and flexibility) at a reduced cost, size and power for all scales of the vision
- Much more work is needed at all scales to realize this vision of multi-terabit-per-second cooperative microsystems

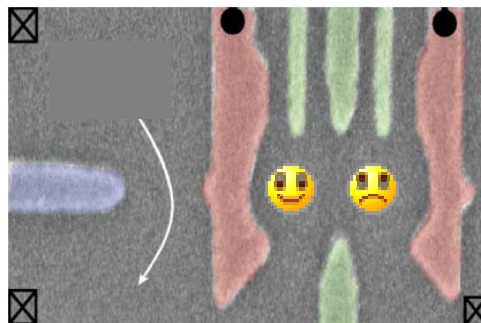


Cooperative Microsystems at a Quantum Scale



Here, the subsystems are quantum states, e.g., electron spin states, photon polarization states, atomic states, etc., and the interconnect is quantum entanglement, “*the spooky action at a distance*”

Entanglement of electron spins in quantum dots defined by gate voltages



Two Talks:

- Charles Marcus (Harvard) – **Cooperative Quantum Microsystems**
- Charles Bennett (IBM) – **The Promise of Quantum Key Distribution**

Today, scientists have succeeded in realizing secure Quantum Key Distribution (QKD) over ~100-km free-space or fiber-optic links using the **BB84 Protocol** conceived by **Bennett and Brassard** in 1984

The holy grail of QKD is to extend the distance to continental scale, using entanglement-based “**quantum repeaters**”



Part of the vision in this sub-session is related to the **DARPA QuEST Program**



And finally for something completely different !



A Talk by:

- Joe Pancrazio (NIH) – on
**“Prosthetics, Interconnects,
Neuro-Photonics”**

Note that *Interconnects* is a common theme,
other than that, it is a completely different story

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MTO SYMPOSIUM

The logo for the Microsystems Technology Office (MTO) Symposium. It features the letters "MTO" in a large, bold, metallic font. The "O" is a circle containing a globe with the word "DARPA" on it. Circuit traces extend from the "M" and "O". Below "MTO" is the word "SYMPOSIUM" in a smaller, white, sans-serif font. The entire logo is set against a dark background with a reflection effect below it.

BUILDING THE FUTURE
FROM THE INSIDE OUT

The background of the poster is a collage of various technological and infrastructure elements. On the left, there's a large satellite dish and a solar panel array. In the center, a complex antenna structure is visible. On the right, there's a large, modern building with a glass facade. The entire background is in shades of blue and white, with a grid pattern overlaid. A thin blue line with three blue spheres runs horizontally across the middle of the image.

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